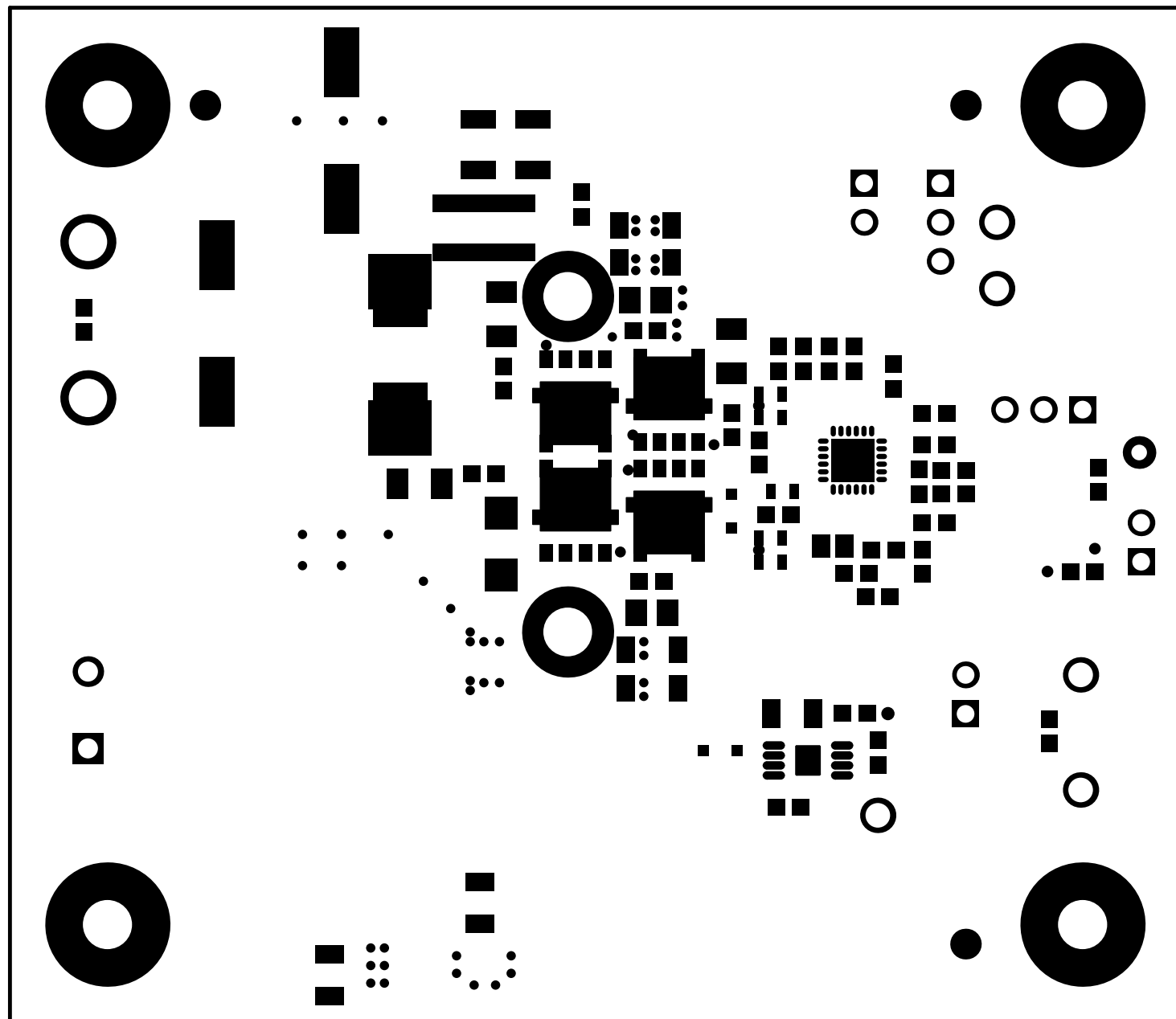
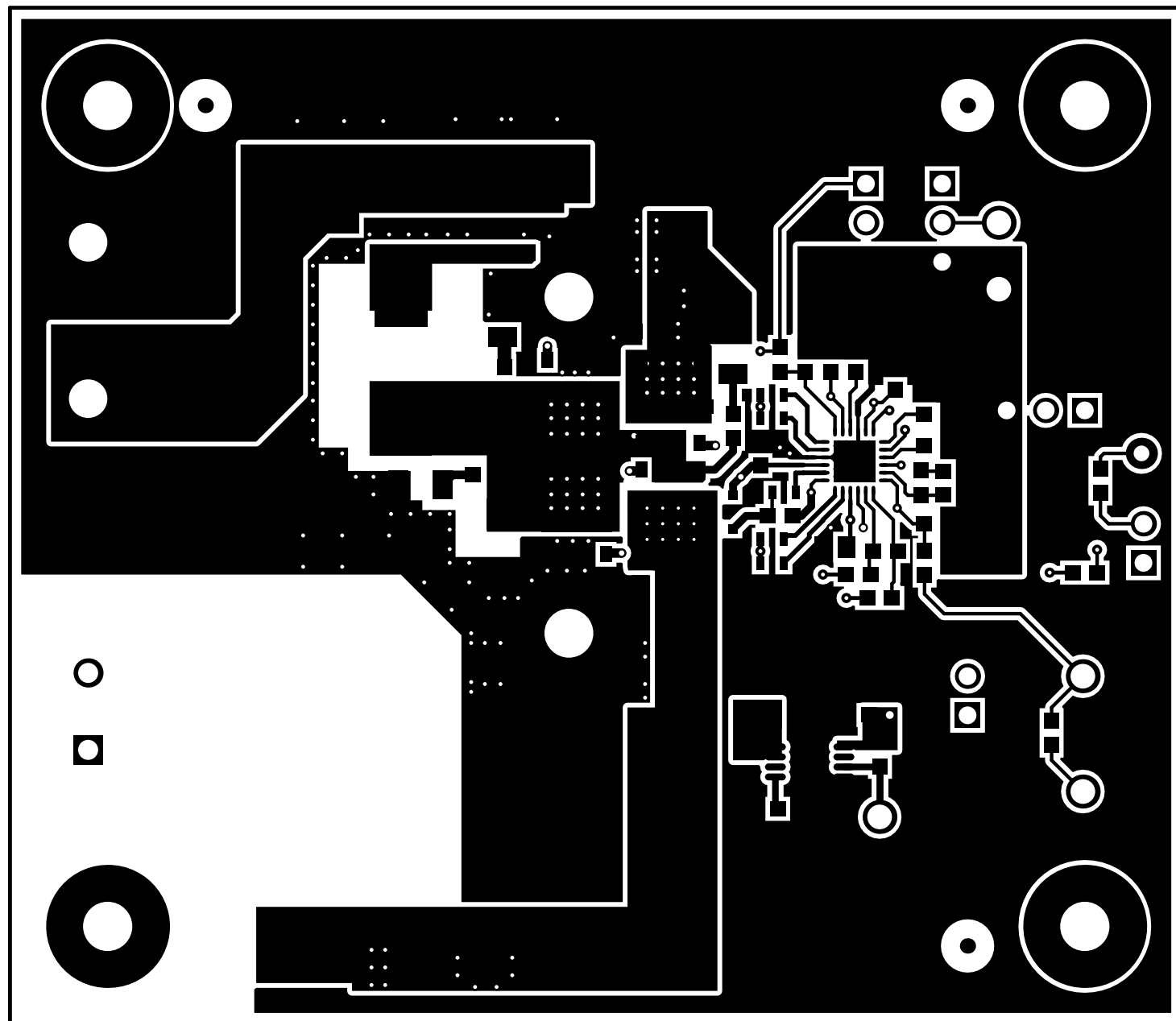


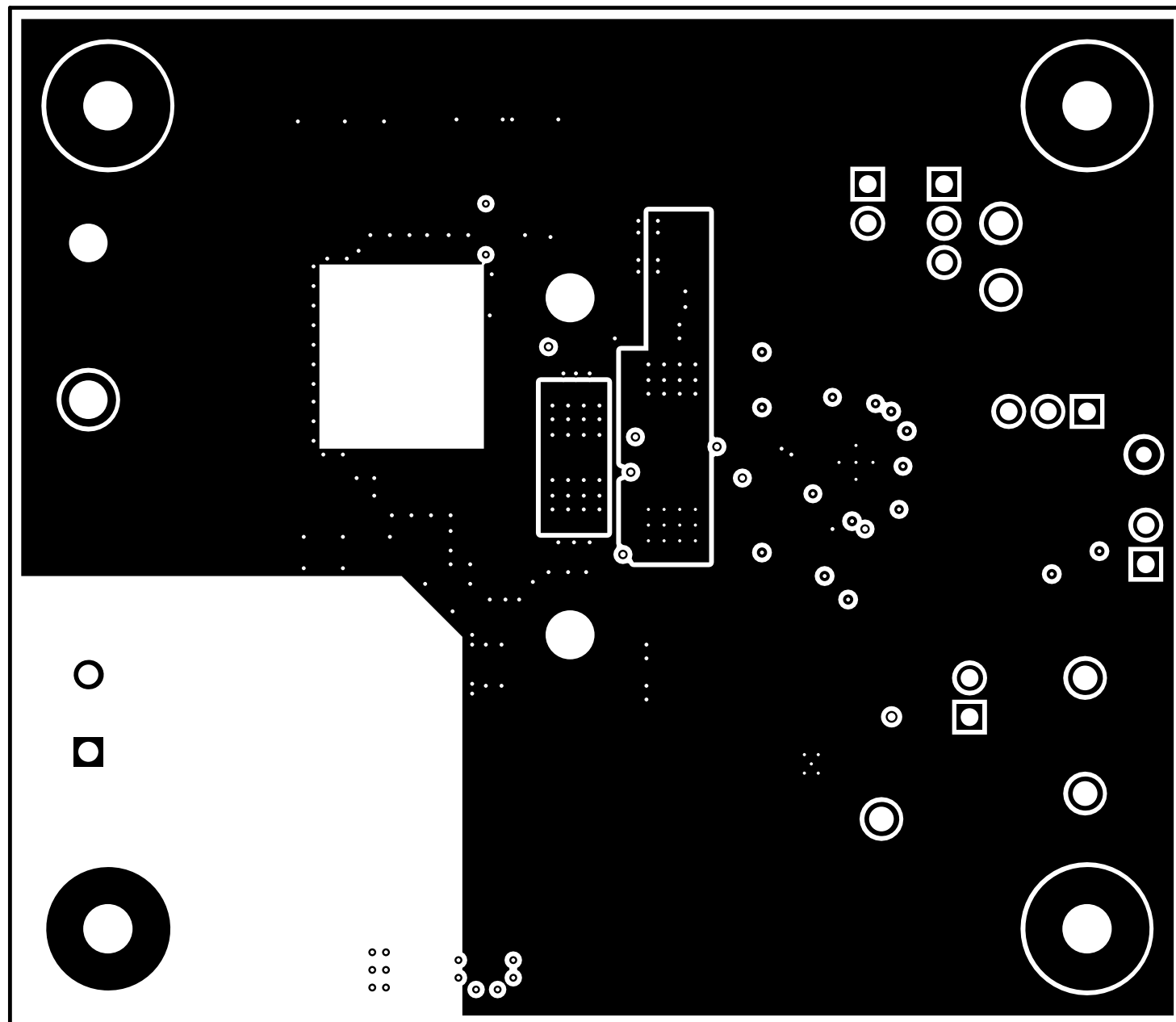
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: PMP20387		
PLOT NAME = Top Overlay	GENERATED : 12/3/2017	1:21:52 PM	TEXAS INSTRUMENTS



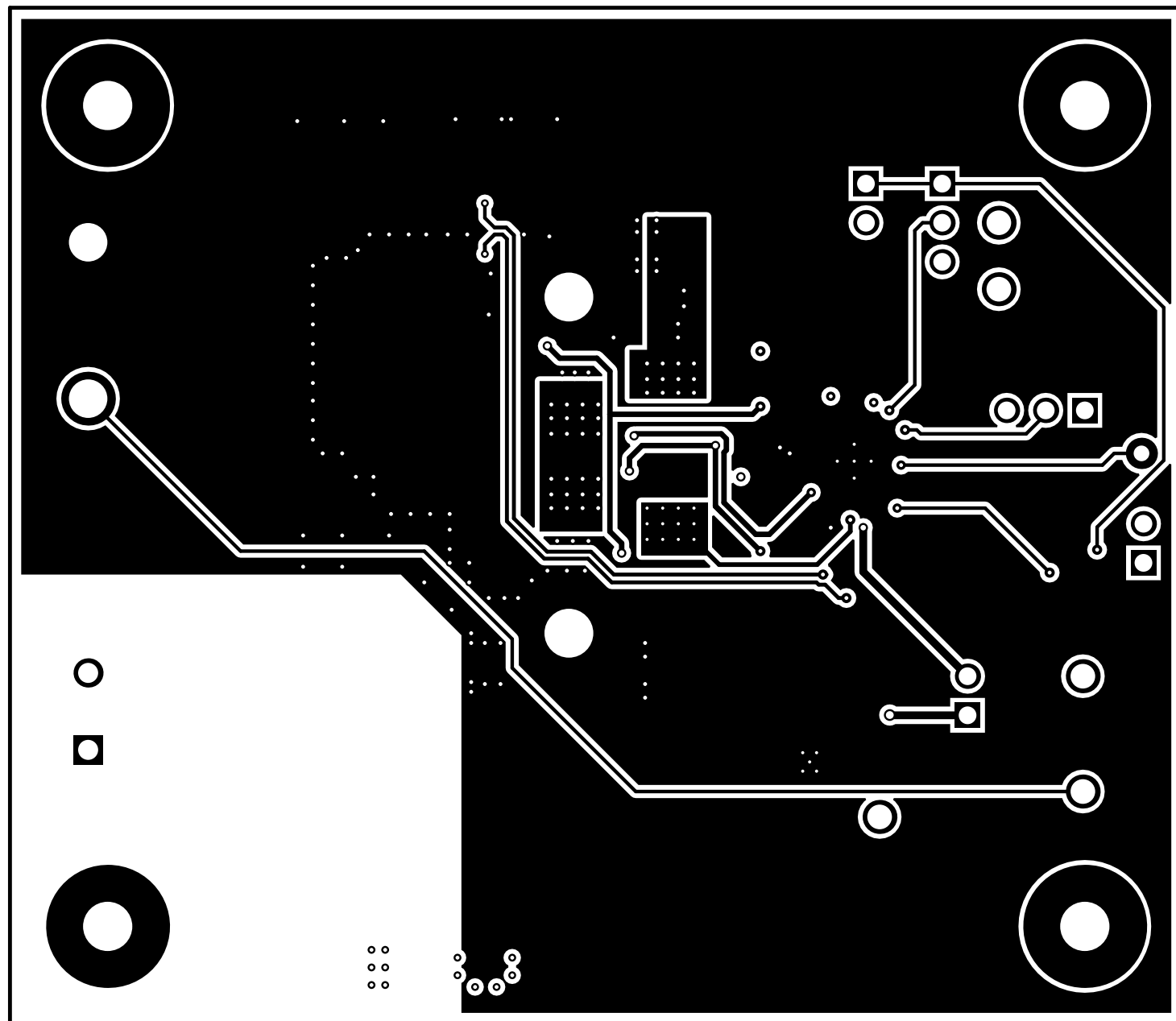
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: PMP20387		
PLOT NAME = Top Solder Mask	GENERATED : 12/3/2017 1:21:55 PM	TEXAS INSTRUMENTS	



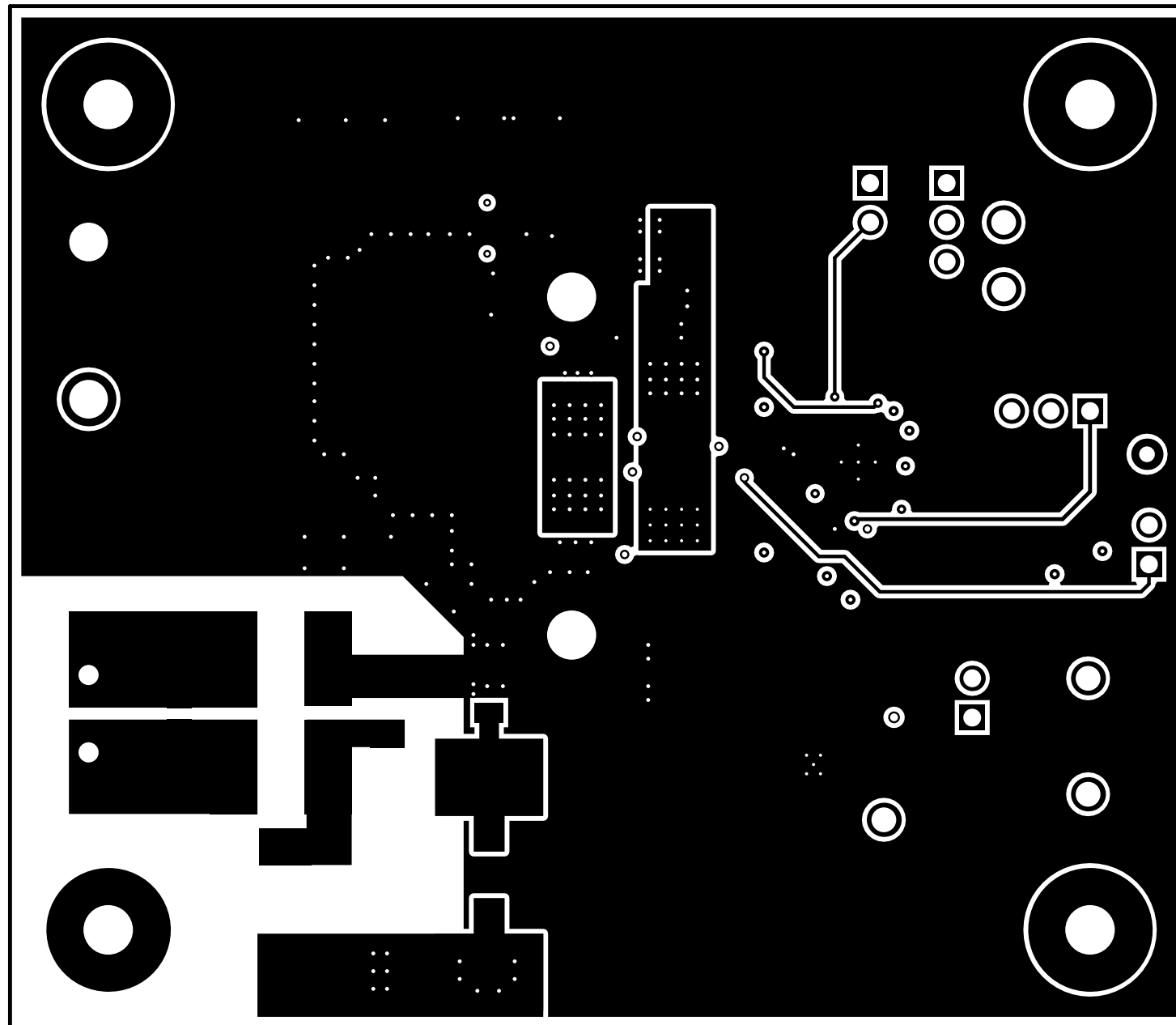
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TID #: PMP20387		
PLOT NAME = Top Layer	GENERATED : 12/3/2017 1:21:57 PM	TEXAS INSTRUMENTS	



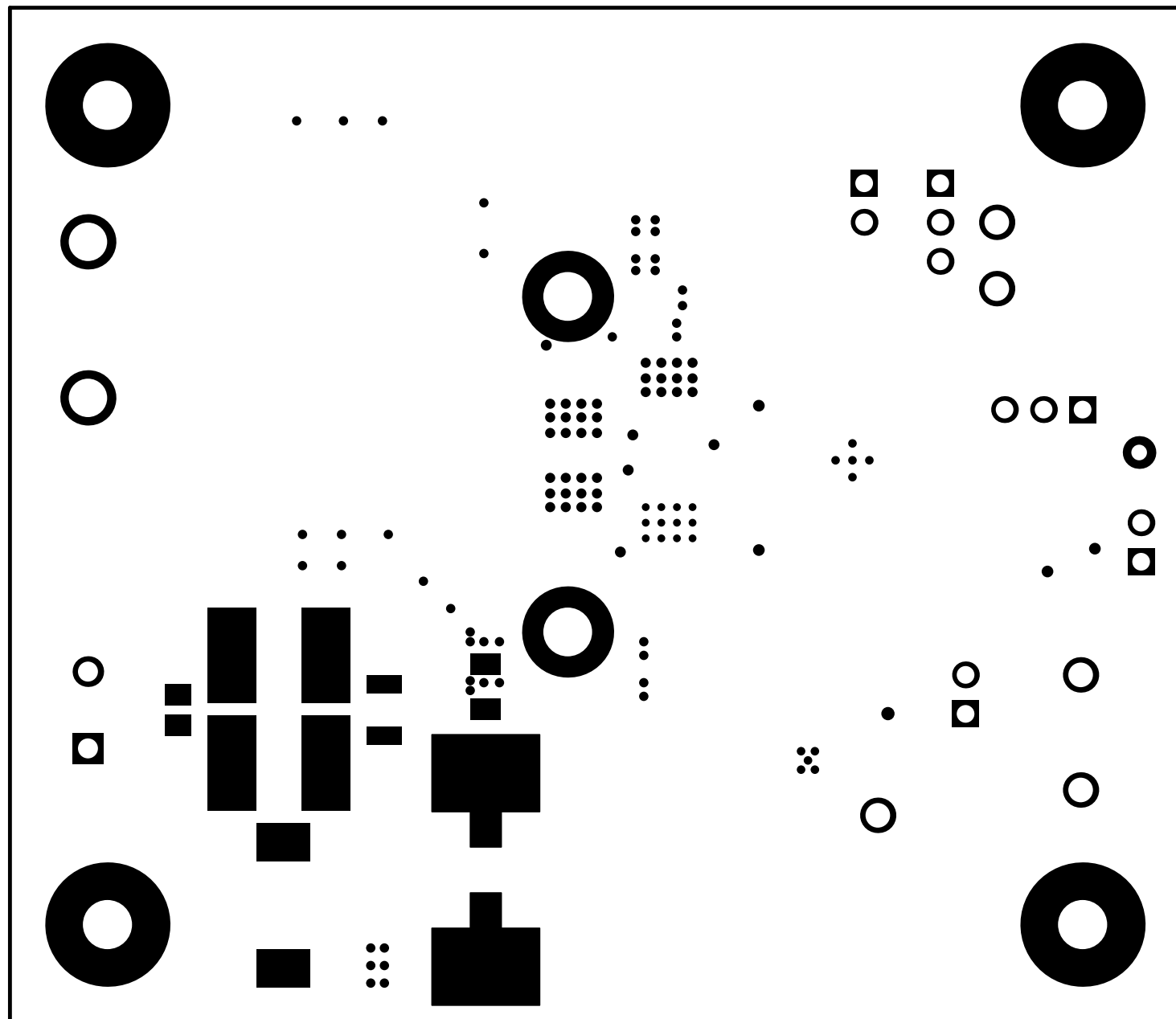
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 1	TID #: PMP20387		
PLOT NAME = Signal Layer 1	GENERATED : 12/3/2017 1:21:59 PM	TEXAS INSTRUMENTS	



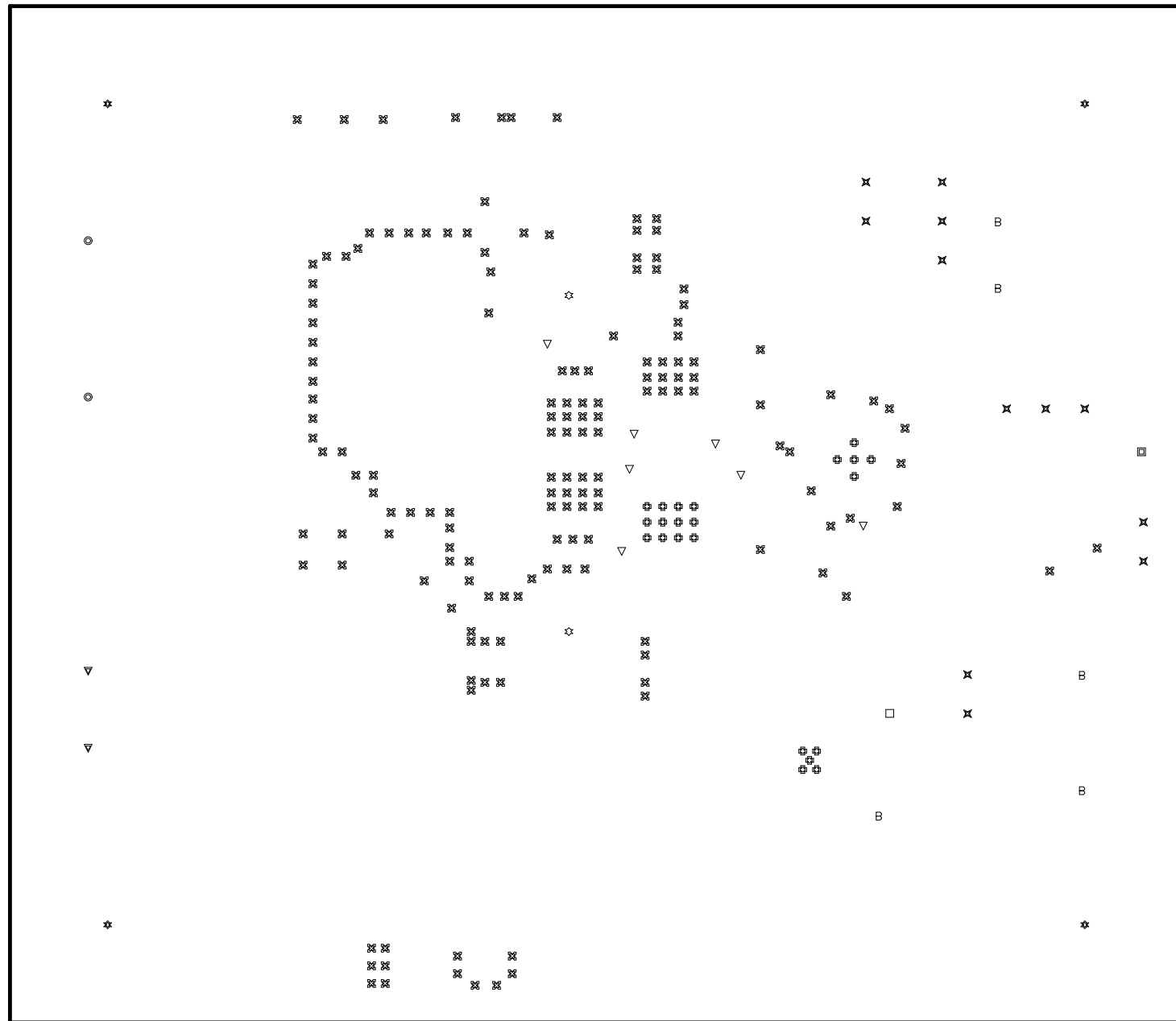
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Signal Layer 2	TID #: PMP20387		
PLOT NAME = Signal Layer 2	GENERATED : 12/3/2017 1:22:01 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TID #: PMP20387		
PLOT NAME = Bottom Layer	GENERATED : 12/3/2017 1:22:04 PM	TEXAS INSTRUMENTS	

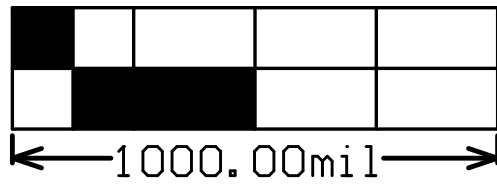


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: PMP20387		
PLOT NAME = Bottom Solder Mask	GENERATED : 12/3/2017 1:22:07 PM	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
⊕	22	8.00mil (0.203mm)	PTH	Round
⊗	157	10.00mil (0.254mm)	PTH	Round
▽	7	14.00mil (0.356mm)	PTH	Round
□	1	20.00mil (0.508mm)	PTH	Round
■	1	40.00mil (1.016mm)	PTH	Round
⊗	12	45.28mil (1.150mm)	PTH	Round
▽	2	51.18mil (1.300mm)	PTH	Round
B	5	63.00mil (1.600mm)	PTH	Round
⊕	2	98.43mil (2.500mm)	PTH	Round
⊗	2	125.00mil (3.175mm)	PTH	Round
⊗	4	125.98mil (3.200mm)	PTH	Round
	215 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: PMP20387		
PLOT NAME = Drill Drawing	GENERATED : 12/3/2017	1:22:14 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20387	REV: A	SVN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: PMP20387		
PLOT NAME = Board Dimensions	GENERATED : 12/3/2017 1:22:21 PM		TEXAS INSTRUMENTS

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